

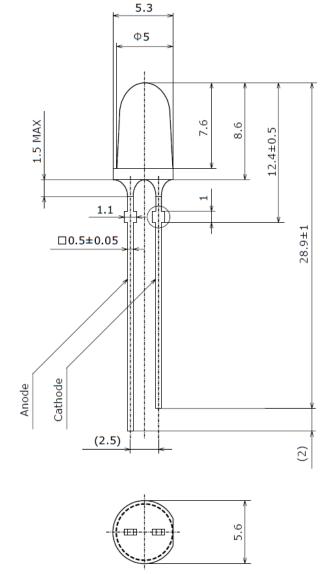
5mm Blue LED Lamp with Stand Off

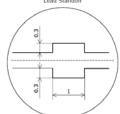
DESCRIPTION

- Round Type
- 5mm Diameter
- Lens Color: Water Clear
- With Flange
- · Solder leads with standoffs

FEATURES

- Emitted Color: Blue
- High Luminous Intensity
- Viewing Angle: 15°





NOTES:

1. All dimensions are in millimeters tolerance is ±0.25mm unless otherwise noted;

Part Number	Lens Color		
rait Nullibei	Emitted	Lens	
L513UBC-S	Blue	Water Clear	



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ABSOLUTE MAXIMUM RATINGS

(Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I _F	35	mA
Peak Pulsed Forward Current	I _{FP}	110	mA
Reverse Voltage	V _R	5	V
Power Dissipation	Pd	123	mW
Operating temperature range	Topr	-30~+85	°C
Storage temperature range	Tstg	-40~+100	°C
Junction Temperature	Tj	100	°C

OPTICAL-ELECTRICAL CHARACTERISTICS

(Ta=25°C)

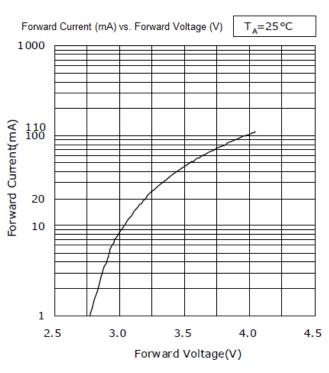
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Reverse Current	I _R	V _R =5V	1	1	50	μA
Forward Voltage	V_{F}		2.6	3.2	3.5	V
Luminous Intensity	l _V		4880	9750	13950	mcd
Dominant Wavelength		I _F =20mA		470		nm
Chromaticity Coordinate	х			0.133		
Chromaticity Coordinate	у			0.075		

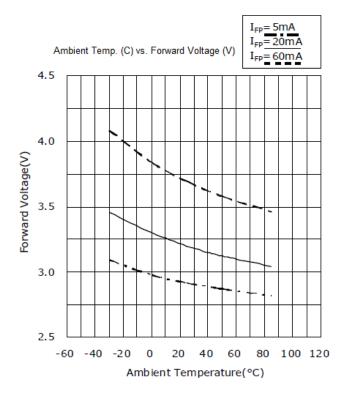
^{*}Note: I_{FP} = Pulse Width ≤ 10ms, Duty Ratio ≤ 1/10

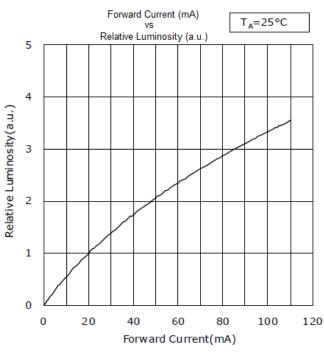


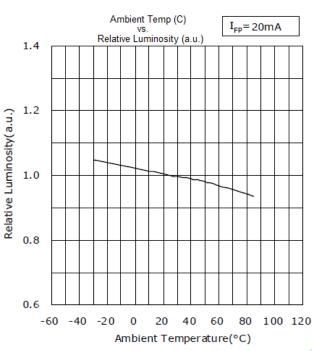
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TYPICAL ELECTRICAL-OPTICAL CHARACTERISTIC CURVES



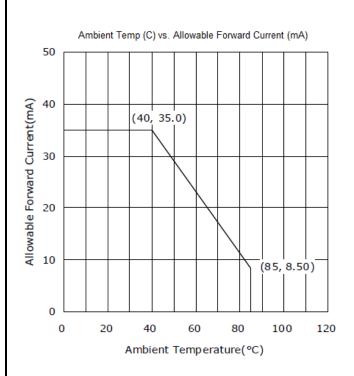


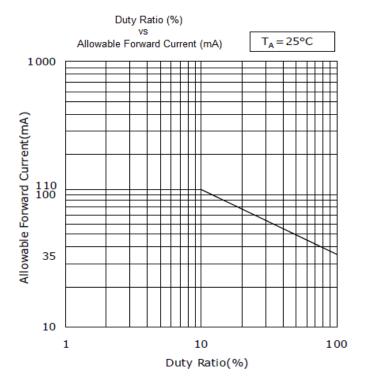


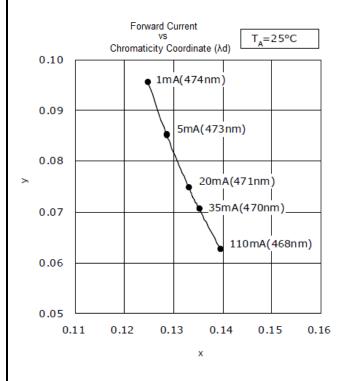


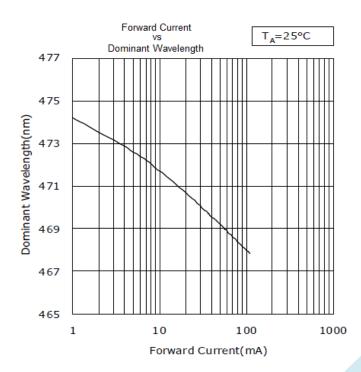


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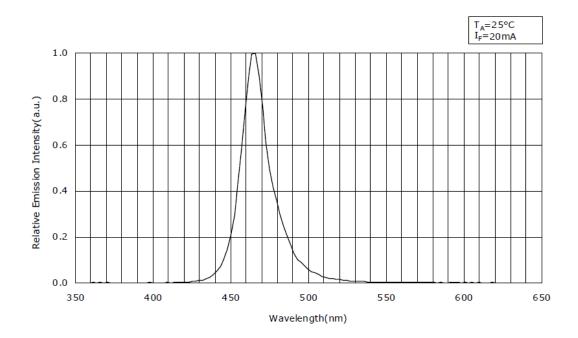




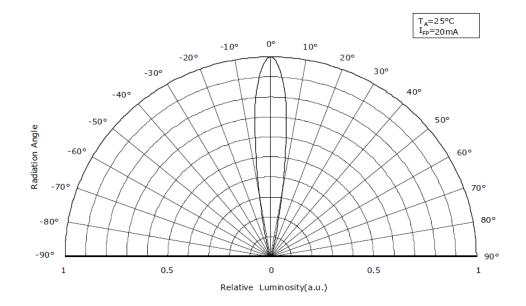


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SPECTRUM



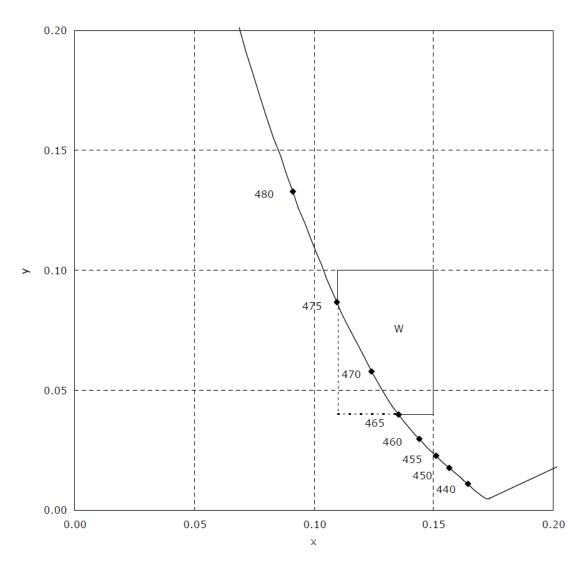
DIRECTIVITY RADIATION





5mm Blue LED Lamp with Stand Off

CHROMATICITY DIAGRAM



COLOR RANK

		Rank W		
X	0.11	0.11	0.15	0.15
Y	0.04	0.10	0.10	0.04



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RELIABILITY

1) Tests and Results

Test	Reference Standard	Test Conditions	Test Duration	Failure Criteria #	Units Failed/Tested
Resistance to	JEITA ED-4701	T _{sld} =260±5°C, 10sec, 1dip,			0/50
Soldering Heat	300 302	3mm from the base of the lens		#1	0/50
Solderability	JEITA ED-4701	T _{sld} =245±5°C, 5sec,		#2	0/50
,	303 303A	Lead-free Solder(Sn-3.0Ag-0.5Cu)			,
Temperature Cycle	JEITA ED-4701 100 105	-40°C(30min)~25°C(5min)~ 100°C(30min)~25°C(5min)	100cycles	#1	0/50
Moisture Resistance (Cyclic)	JEITA ED-4701 200 203	25°C~65°C~-10°C, 90%RH, 24hr per cycle	10cycles	#1	0/50
Terminal Bend Strength	JEITA ED-4701 400 401	5N, 0°~90°~0°bend, 2bending cycles		#1	0/50
Terminal Pull Strength	JEITA ED-4701 400 401	10N, 10±1sec		#1	0/50
High Temperature Storage	JEITA ED-4701 200 201	T _A =100°C	1000hours	#1	0/50
Temperature Humidity Storage	JEITA ED-4701 100 103	T _A =60°C, RH=90%	1000hours	#1	0/50
Low Temperature Storage	JEITA ED-4701 200 202	T _A =-40°C	1000hours	#1	0/50
Room Temperature Operating Life		T _A =25°C, I _F =35mA	1000hours	#1	0/50
Temperature Humidity Operating Life		60°C, RH=90%, I _F =20mA	500hours	#1	0/50
Low Temperature Operating Life		T _A =-30°C, I _F =20mA	1000hours	#1	0/50

Note: Measurements are performed after allowing the LEDs to return to room temperature.

2) Failure Criteria

Criteria #	Items	Conditions	Failure Criteria
	Forward Voltage(V _F)	I _F =20mA	>U.S.L.×1.1
#1	Luminous Intensity(I _v)	I _F =20mA	<l.s.l.×0.7< td=""></l.s.l.×0.7<>
	Reverse Current(I _R)	V _R =5V	>U.S.L.×2.0
#2	Solderability	-	Less than 95% solder coverage

U.S.L.: Upper Specification Limit L.S.L.: Lower Specification Limit



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SOLDERING CONDITIONS – LAMP TYPE LED

- Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- Recommended soldering conditions.

Dip Soldering		
Pre-Heat Pre-Heat Time Solder Bath Temperature Dipping Time Dipping Position	100°C Max. 60 sec. Max. 260°C Max. 5 sec. Max. No lower than 3mm from the base of the epoxy bulb.	

Hand Soldering				
	3Ø Series	Others (Including Lead-Free Solder)		
Temperature Soldering time Position	300°C Max. 3 sec. Max. No closer than 3mm from the base of the epoxy bulb.	350°C Max. 3 sec. Max. No closer than 3mm from the base of the epoxy bulb.		

- Do not apply any stress to the lead, particularly when heated
- The LEDs must not be repositioned after soldering
- After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be
 caused by the PC board warping or from the clinching and cutting of the leadframes. When it is
 absolutely necessary, the LEDs may be mounted in this fashion, but the User will assume
 responsibility for any problems. Direct soldering should only be done after testing has confirmed
 that no damage, such as wire bond failure or resin deterioration, will occur. AOP's LEDs should
 not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy
 resin.
- When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- Cut the LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause LED failure.